

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 3723**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyoshi TOMINAGA et al.

Group Art Unit: 3723

Application No.: 10/500,278

Examiner: M. RACHUBA

Filed: June 29, 2004

Docket No.: 120214

For: WAFER DOUBLE-SIDE POLISHING APPARATUS AND DOUBLE-SIDE  
POLISHING METHOD

**REQUEST FOR RECONSIDERATION AFTER FINAL REJECTION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In reply to the November 29, 2006 Office Action, reconsideration of the rejection is  
respectfully requested in light of the following remarks.